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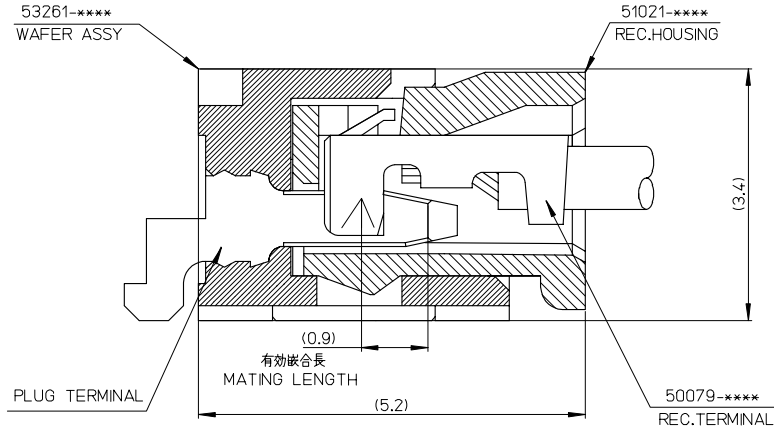
[Molex Connector Corporation](#)
[0532611071](#)

For any questions, you can email us directly:

sales@integrated-circuit.com

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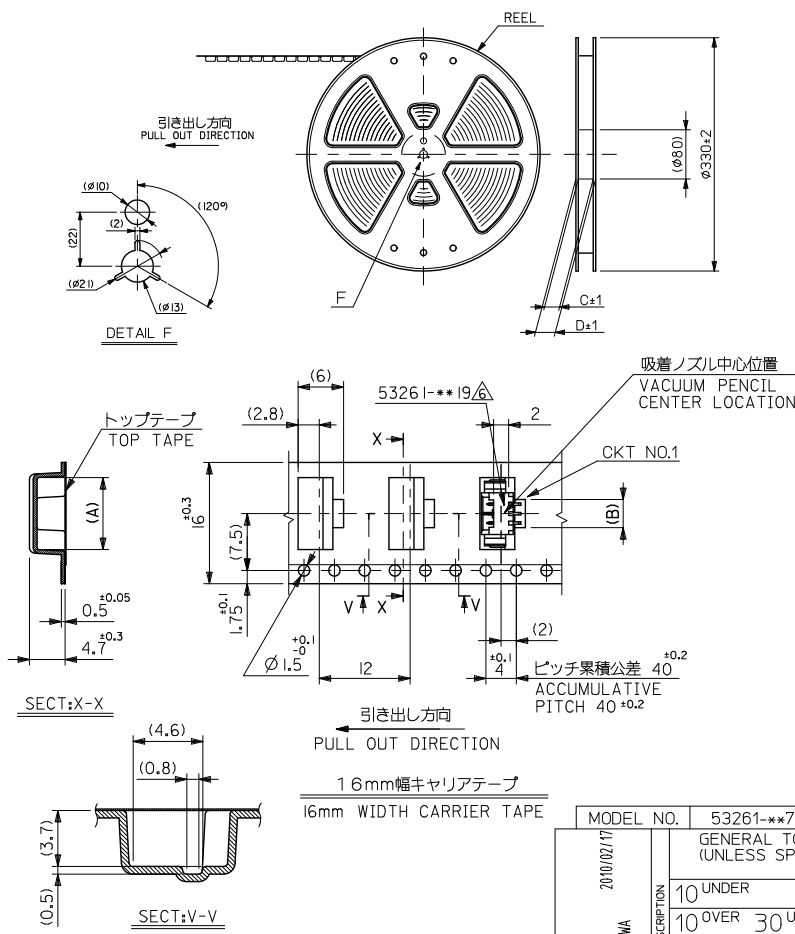
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53261-****	WAFER ASSY	MODEL NO./MATERIAL NO.
50079-****	TERMINAL	
51021-****	HOUSING	

RELEASED EC NO: J2006-2426 DRAWN: A0YAGI CHKD: MAEDA APPR: NIKITA 2006/02/02 2006/02/03 2006/02/07	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±---	DRAWN BY Y. A0YAGI	DATE 2006/01/30	TITLE 1.25 W-T-O-B CONN. 51021,53261 MATING CROSS SECTION		
	10 OVER 30 UNDER	±---	CHECKED BY Y. MAEDA	DATE 2006/01/30	MOLEX INCORPORATED		
	30 OVER	±---	APPROVED BY N. UKITA	DATE 2006/01/30	MATERIAL NO. SEE CHART DOCUMENT NO. SD-51021-002		
0	ANGULAR	±---°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SHEET NO. 1 OF 1		

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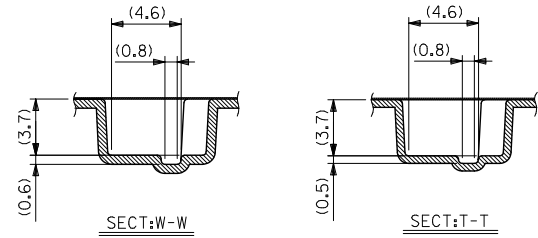
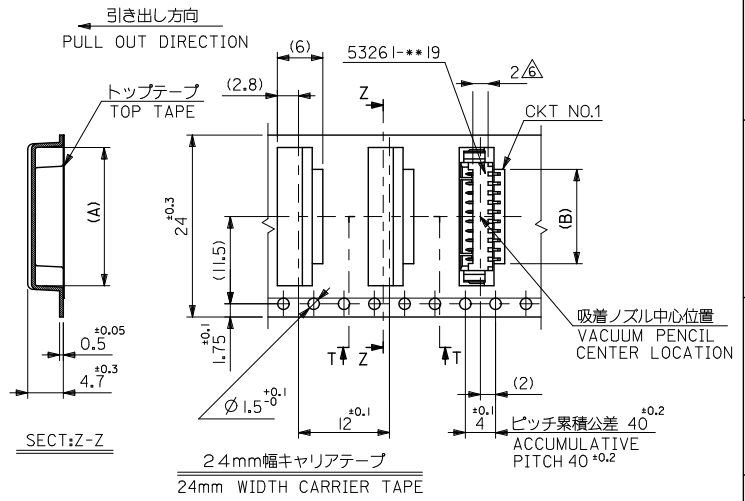
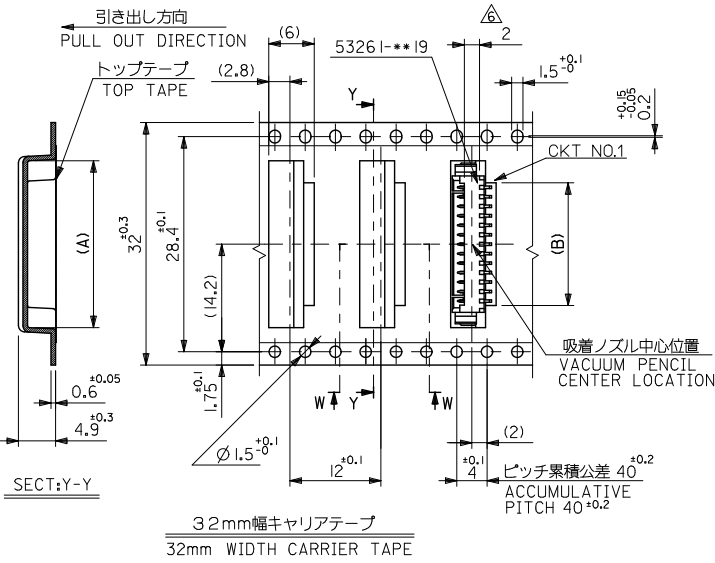


**注記
NOTES**

- 53261-**-19 の詳細寸法については図面 SD-53261-024 を参照下さい。
RE DETAILED DIMENSIONS, SEE SD-53261-024
 - 梱包数量: 1000個/リール
NUMBER OF CONNECTOR: 1000PCS/REEL
 - リードテープ長さ LEAD TAPE LENGTH
トップテープリーダ部 TOP TAPE LEADER PART トップテープ未接着部 TOP TAPE NON-BONDED PART
175⁺²⁵ 25⁺⁵
-
- 材料 (MATERIAL)
キャリアテープ (CARRIER TAPE): ポリプロピレン (POLYPROPYLENE)
トップテープ (TOP TAPE): PET, PE, PEF
リール (REEL): ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>
- △ コネクタ、ハウジング平面部
CONNECTOR, HOUSING FLAT AREA
- 本製品は 53261-**-90 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**-90
 - ELV及びRoHS適合品
ELV AND RoHS COMPLIANT
 - 本製品は乾燥剤入り、ハイバリア梱包仕様である。
THIS PRODUCT IS HIGH BARRIER PACKAGE WITH DESICCANT.

6	21.4	17.4	3.7	9.5	53261-037I	3	
			2.45	8.25	53261-027I	2	
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	EMBOSSED TAPE PACKAGE オーダー番号 ORDER NO.	極数 CKT.	
MODEL NO.	53261-**-71		DIMENSION STYLE MM ONLY		SCALE ---	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
REVISED	DESCRIPTION		DRAWN BY DATE		TITLE		
EC NO.	DRAWN: GOTO CHKD: KAKAWA		H. SHIMABUKUR '04/02/06		1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
REV	10 UNDER ±0.2		CHECKED BY DATE		MOLEX INCORPORATED		
	10 OVER 30 UNDER ±0.25		K. TOJO '04/02/06		SD-53261-023		
	30 OVER ±0.3		APPROVED BY DATE		SHEET NO.		
	ANGULAR ±3 °		NUKITA 2010/02/18		1 OF 3		
	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		MATERIAL NO.		DOCUMENT NO.		
			SEE TABLE & SHEET 2.3		INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
			SIZE				
			A3				

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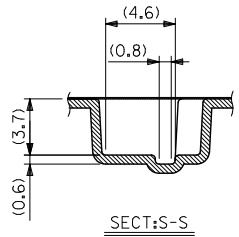
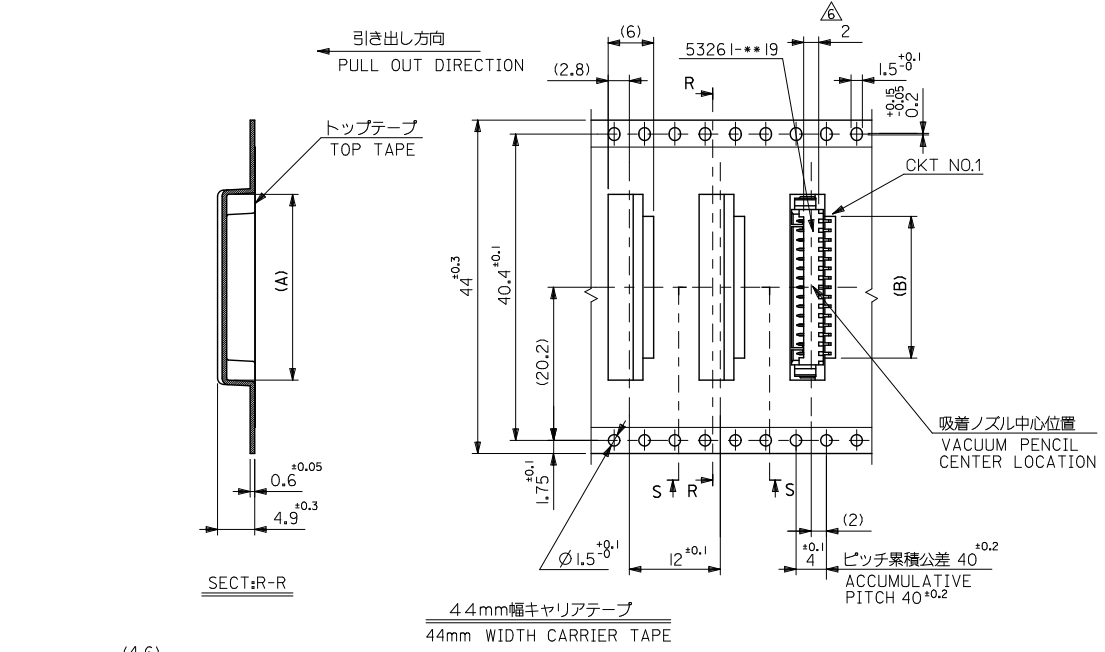


32	37.4	33.4	16.2	22	53261-1371	13
			14.95	20.75	-1271	12
24	29.4	25.4	13.7	19.5	-1171	11
			12.45	18.25	-1071	10
			11.2	17	-0971	9
			9.95	15.75	-0871	8
			8.7	14.5	-0771	7
			7.45	13.25	-0671	6
			6.2	12	-0571	5
			4.95	10.75	53261-0471	4

MODEL NO.	53261-***71	DIMENSION STYLE	MM ONLY	SCALE	---	DESIGN UNITS	METRIC	THIRD ANGLE PROJECTION
GENERAL TOLERANCES (UNLESS SPECIFIED)		DRAWN BY	H. SHIMABUKUR	DATE	'04/02/06	TITLE		
10 UNDER	± 0.2	CHECKED BY	K. TOJO	DATE	'04/02/06	1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG		
10 OVER	± 0.25	APPROVED BY	NUKITA	DATE	2010/02/18	MOLEX INCORPORATED		
30 OVER	± 0.3	MATERIAL NO.		DOCUMENT NO.	SD-53261-023	SHEET NO. 2 OF 3		
ANGULAR	± 3 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE & SHEET 1.3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

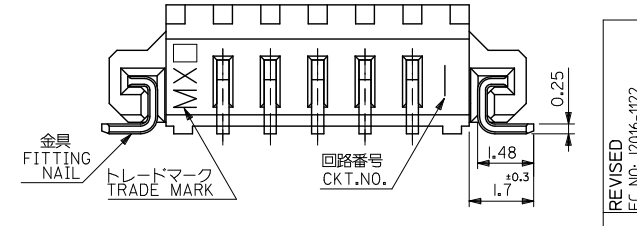
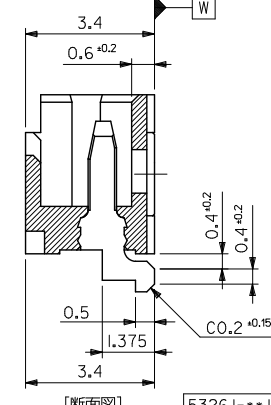
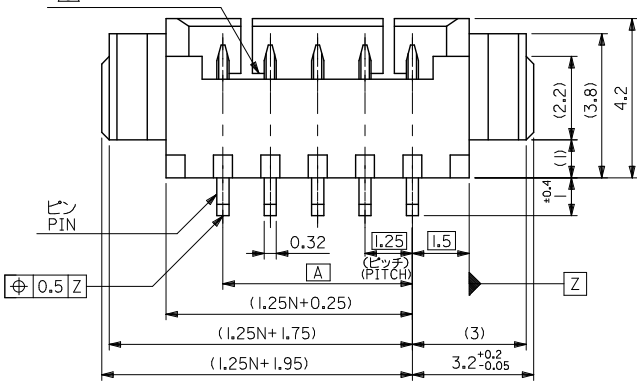
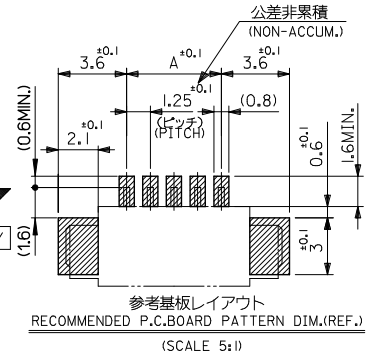
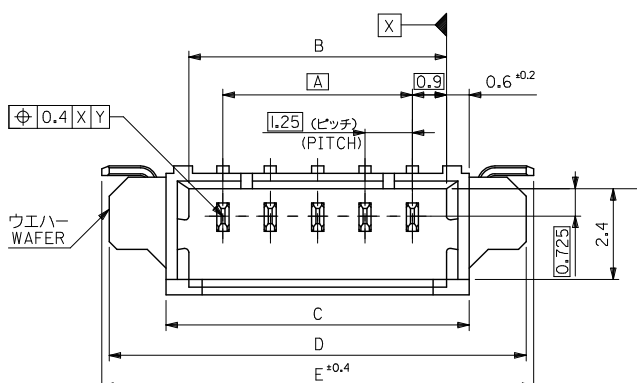
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MODEL NO.	53261-1571	44	49.4	45.4	18.7	24.5	53261-1571	15
キャリアテープ幅 CARRIER TAPE WIDTH	D	C	B	A	17.45	23.25	53261-1471	14
EMBOSSED TAPE PACKAGE	種数 CKT.		EMBOSSED TAPE PACKAGE 種数					
ORDER NO.	ピッチ累積公差 40±0.2		ACCUMULATIVE PITCH 40±0.2					
GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE		SCALE		DESIGN UNITS		THIRD ANGLE PROJECTION	
10 UNDER ±0.2	MM ONLY		---		METRIC		☉ □	
10 OVER 30 UNDER ±0.25	DRAWN BY H. SHIMABUKUR		DATE '04/02/06		TITLE 1.25 W/B CONN WAFER ASSY FOR SMT EMBSTP PKG			
30 OVER ±0.3	CHECKED BY K. TOJO		DATE '04/02/06		MOLEX INCORPORATED			
ANGULAR ±3°	APPROVED BY NUKITA		DATE 2010/02/18		DOCUMENT NO. SD-53261-023			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO.		SEE TABLE & SHEET 12		SHEET NO. 3 OF 3			
	SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION					

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- 注記 NOTES**
1. 嵌合相手: 51021 シリウス
MATES WITH: 51021 SERIES
 2. 材質 MATERIAL
ワエハー: NYLON46, UL94V-0
ピン: リン青銅
PIN: PHOS-BRO
銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1.0 マイクロメートル以上
: NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
 3. 金具
FITTING NAIL: PHOS-BRO
銅メッキ 1.0 マイクロメートル以上
: TIN 1.0 MICROMETER MINIMUM
ニッケル下地 1.0 マイクロメートル以上
: NICKEL UNDER PLATING 1.0 MICROMETER MINIMUM
 4. ロック窓は 2, 3 種は 1 箇所, 4 種以上は 2 箇所とする。
LOCKING WINDOW: ONE PLACE FOR 2 AND 3 CKT. AND TWO PLACES FOR MORE THAN 3 CKT.
ソルダーテール部のスリ量及び金具(補強板)のスリ量は基準面 [W] に対し、上方向 0.05MAX.、下方向に 0.1 MAX. とする。
OFFSET BETWEEN BASIS PLANE [W] TO SOLDER TAIL BOTTOM AND FITTING NAIL BOTTOM:
UPPER SIDE: 0.05MAX.
LOWER SIDE: 0.1MAX.
 5. 本製品は 53261-**10 の鉛フリー品である。
THIS PRODUCT IS LEAD FREE OF 53261-**10
 6. ELV 及び RoHS 適合品
ELV AND RoHS COMPLIANT.
 7. ソルダーテール及び金具の平直度は 0.1 以下。
SOLDER TAIL & FITTING NAIL COPLANARITY TO BE 0.1 MAX.

26.4	26	23	21.8	20	53261-1771	53261-1719	17
23.9	23.5	20.5	19.3	17.5	-1571	-1519	15
22.65	22.25	19.25	18.05	16.25	-1471	-1419	14
21.4	21	18	16.8	15	-1371	-1319	13
20.15	19.75	16.75	15.55	13.75	-1271	-1219	12
18.9	18.5	15.5	14.3	12.5	-1171	-1119	11
17.65	17.25	14.25	13.05	11.25	-1071	-1019	10
16.4	16	13	11.8	10	-0971	-0919	9
15.15	14.75	11.75	10.55	8.75	-0871	-0819	8
13.9	13.5	10.5	9.3	7.5	-0771	-0719	7
12.65	12.25	9.25	8.05	6.25	-0671	-0619	6
11.4	11	8	6.8	5	-0571	-0519	5
10.15	9.75	6.75	5.55	3.75	-0471	-0419	4
8.9	8.5	5.5	4.3	2.5	-0371	-0319	3
7.65	7.25	4.25	3.05	1.25	53261-0271	53261-0219	2

REVISED EC NO. J2016-1122 DRAWING#31 CHKD: SAKIYAMA APPR: IKANEKO 2016/04/26 2016/05/06 2016/05/06	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	EMBOSSED TAPE PKG ORDER NO.	MATERIAL NO.	種数 CKT.
	0.25 UNDER	UNDER	±0.03	DRAWN BY HSI MABU	DATE 04/02/06	TITLE 1.25 WIRE TO BOARD WAFER ASS FOR SMT			
0.25 OVER	0.5 UNDER	±0.05	CHECKED BY	DATE					
0.5 OVER	1.0 UNDER	±0.1	APPROVED BY	DATE					
1.0 OVER	10 UNDER	±0.2	MSASAO	04/02/06					
10 OVER	30 UNDER	±0.25	MATERIAL NO.	DOCUMENT NO.					
30 OVER		±0.3	SEE CHART	SD-53261-024					
ANGULAR	±3°		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX ELECTRONIC TECHNOLOGIES, LLC AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION						

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